

ABSTRACT

5 A liquid epoxy resin composition comprising (A) a
liquid epoxy resin, (B) an aromatic amine curing agent
comprising 5-100% by weight of a specific aromatic amine
compound having a purity of at least 99%, (C) an inorganic
filler, and (D) an ester organic solvent having a boiling
point of 130-250°C is useful for semiconductor encapsulation.
10 The composition has an infiltration ability, adhesion to
silicon chips, resistance to deterioration under hot humid
conditions, and resistance to thermal shocks.